
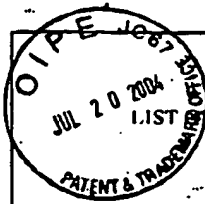


|  <p>LIST OF REFERENCES CITED BY APPLICANT (Use several sheets if necessary)</p> | | | | ATTY. DOCKET NO.: | | APPLICATION SERIAL NO.: | | |
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